

HL6331/32G

Low Operating Current Visible Laser Diode

HITACHI

ADE-208-819 (Z)
Target Specification
1st Edition
Sep. 1999

Description

The HL6331/32G are 0.63 μm band AlGaInP 10mW laser diodes with a multi-quantum well (MQW) structure. They are suitable as light sources for laser levelers, laser scanners and optical equipment for measurement.

Application

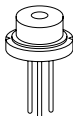
- Laser leveler
- Laser scanner
- Measurement

Features

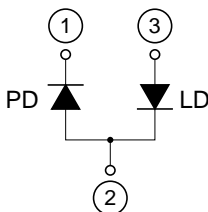
- Visible light output : 635 nm Typ
- Optical output power : 10 mW CW
- Low operating current : 55 mA Typ
- Low operating voltage : 2.4 V Max
- Operating temperature : +60°C
- TM mode oscillation

Internal Circuit

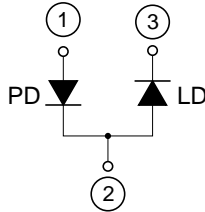
Package Type
• HL6331/32G: G2



Internal Circuit
• HL6331G



Internal Circuit
• HL6332G



Absolute Maximum Ratings (T_C = 25°C)

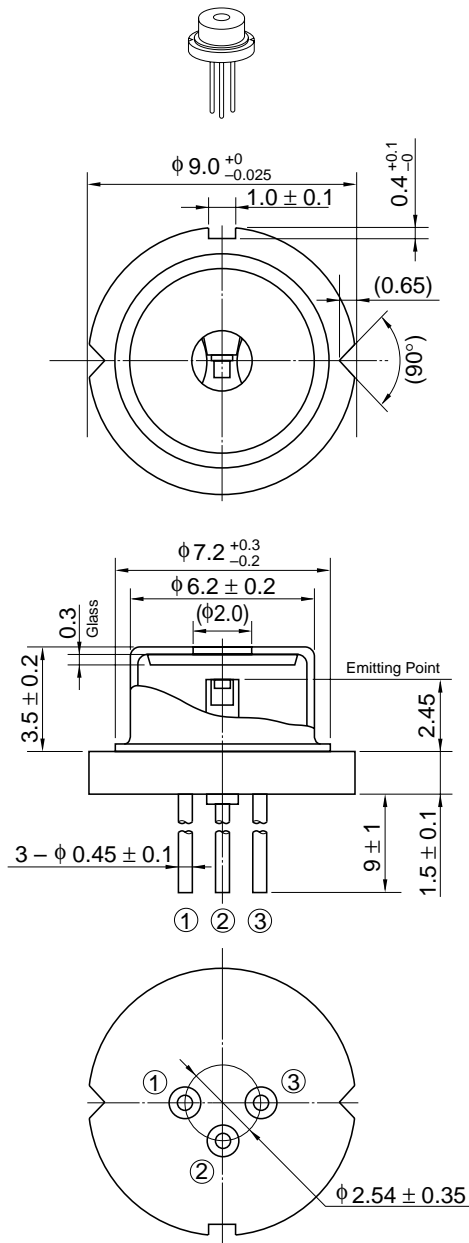
Item	Symbol	Value	Unit
Optical output power	P _O	10	mW
LD reverse voltage	V _{R(LD)}	2	V
PD reverse voltage	V _{R(PD)}	30	V
Operating temperature	T _{opr}	−10 to +60	°C
Storage temperature	T _{stg}	−40 to +85	°C

Optical and Electrical Characteristics (T_C = 25°C)

Item	Symbol	Min	Typ	Max	Unit	Test Condition
Optical output power	P _O	10	—	—	mW	Kink free
Threshold current	I _{th}	—	40	60	mA	
Operating current	I _{op}	—	55	75	mA	P _O = 10 mW
Operating voltage	V _{OP}	—	2.2	2.4	V	P _O = 10 mW
Slope efficiency	η _s	0.3	0.6	0.9	mW/mA	6(mW) / (I _(8mW) − I _(2mW))
Lasing wavelength	λ _p	630	635	640	nm	P _O = 10 mW
Beam divergence parallel to the junction	θ//	6	8	11	deg.	P _O = 10 mW
Beam divergence perpendicular to the junction	θ⊥	25	31	36	deg.	P _O = 10 mW
Monitor current	I _s	—	0.18	—	mA	P _O = 10 mW, V _{R(PD)} = 5V

Package Dimensions

Unit: mm



Hitachi Code	LD/G2
JEDEC	—
EIAJ	—
Weight (reference value)	1.1 g

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1. The laser light is harmful to human body especially to eye no matter what directly or indirectly. The laser beam shall be observed or adjusted through infrared camera or equivalent.

HITACHI

Hitachi, Ltd.

Semiconductor & IC Div.

Nippon Bldg., 2-6-2, Ohte-machi, Chiyoda-ku, Tokyo 100-0004, Japan

Tel: Tokyo (03) 3270-2111 Fax: (03) 3270-5109

URL NorthAmerica : <http://semiconductor.hitachi.com/>
 Europe : <http://www.hitachi-eu.com/hel/ecg>
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For further information write to:

Hitachi Semiconductor
 (America) Inc.
 179 East Tasman Drive,
 San Jose, CA 95134
 Tel: <1> (408) 433-1990
 Fax: <1> (408) 433-0223

Hitachi Europe GmbH
 Electronic components Group
 Dornacher Straße 3
 D-85622 Feldkirchen, Munich
 Germany
 Tel: <49> (89) 9 9180-0
 Fax: <49> (89) 9 29 30 00
 Hitachi Europe Ltd.
 Electronic Components Group.
 Whitebrook Park
 Lower Cookham Road
 Maidenhead
 Berkshire SL6 8YA, United Kingdom
 Tel: <44> (1628) 585000
 Fax: <44> (1628) 778322

Hitachi Asia Pte. Ltd.
 16 Collyer Quay #20-00
 Hitachi Tower
 Singapore 049318
 Tel: 535-2100
 Fax: 535-1533

Hitachi Asia Ltd.
 Taipei Branch Office
 3F, Hung Kuo Building, No.167,
 Tun-Hwa North Road, Taipei (105)
 Tel: <886> (2) 2718-3666
 Fax: <886> (2) 2718-8180

Hitachi Asia (Hong Kong) Ltd.
 Group III (Electronic Components)
 7/F., North Tower, World Finance Centre,
 Harbour City, Canton Road, Tsim Sha Tsui,
 Kowloon, Hong Kong
 Tel: <852> (2) 735 9218
 Fax: <852> (2) 730 0281
 Telex: 40815 HIITEC HX

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